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 Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450  
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Signed: Paula Faulk Hurley  
 Paula Faulk Hurley

Application No. 10/632,550  
 Attorney Docket: CPAC 1017-7 D5

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Marcos Kamenzos	Attorney Docket No.: CPAC 1017-7 D5
Application No.: 10/632,550	Examiner: Mai-Huong Tran
Filed: 02 August 2003	Group: 2811
Title: Semiconductor Multi-Package Module Including Stacked-Die Packages And Having Wire Bond Interconnect Between Stacked Packages	Confirmation No.: 2570
	Customer No. 22470

## INFORMATION DISCLOSURE STATEMENT AFTER ALLOWANCE

Commissioner for Patents  
 P.O. Box 1450  
 Alexandria, VA 22313-1450

Sr:

Applicants submit the below-listed documents to be placed in the file:

- Takahashi et al., U. S. Patent No. 6,025,648 issued 15 February 2000 for "Shock Resistant Semiconductor Device and Method for Producing Same".

Respectfully submitted,  
 Thomas Boffel & Wolfeld LLP

Date: 11 May 2005  
 By: Bill Kennedy  
 Bill Kennedy, Reg. No. 33,407

Bill Kennedy  
 Haynes Boffel & Wolfeld LLP  
 P.O. Box 366  
 Half Moon Bay, CA 94019  
 Ph. (650) 712-0340  
 Fax (650) 712-0263

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